MOSFETs Silicon N-Channel MOS (U-MOSVI-H)

# **TPCC8061-H**

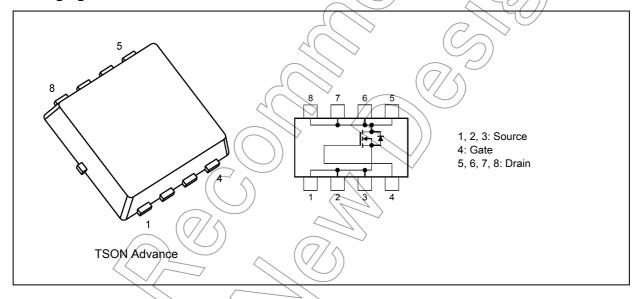
### 1. Applications

- High-Efficiency DC-DC Converters
- · Notebook PCs
- · Mobile Handsets

#### 2. Features

- (1) Small, thin package
- (2) High-speed switching
- (3) Small gate charge:  $Q_{SW} = 3.5 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 21 \text{ m}\Omega$  (typ.) ( $V_{GS} = 4.5 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- (6) Enhancement mode:  $V_{th} = 1.3 \text{ to } 2.3 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 0.1 \text{ mA})$

### 3. Packaging and Internal Circuit





## 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Character	Symbol	Rating	Unit		
Drain-source voltage			$V_{DSS}$	30	V
Gate-source voltage			$V_{GSS}$	±20	
Drain current (DC)		(Note 1)	I <sub>D</sub>	8	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	24	
Power dissipation	(T <sub>c</sub> = 25°C)		P <sub>D</sub>	15	W
Power dissipation	(t = 10 s)	(Note 2)	P <sub>D</sub>	1.9	W
Power dissipation	(t = 10 s)	(Note 3)	Pp	0.7	W
Single-pulse avalanche energy		(Note 4)	EAS	)) 41	mJ
Avalanche current			I <sub>AR</sub>	8	Α
Channel temperature			(T <sub>ch</sub> )	150	°C
Storage temperature		6	T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

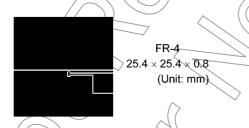
Cha	aracteristics			Symbol	Max	Unit
Channel-to-case thermal resistance		(T <sub>c</sub> = 25°C)		R <sub>th(ch-c)</sub>	8.33	°C/W
Channel-to-ambient thermal resistance		(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	65.7	°C/W
Channel-to-ambient thermal resistance		(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	178	°C/W

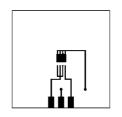
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{DD} = 24 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH,  $R_G = 1.2 \Omega$ ,  $I_{AR} = 8 \text{ A}$ 





 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$ 

Fig. 5.1 Device Mounted on a Glass-Epoxy
Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μΑ
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	_	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30			V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	(15	7		
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.1 mA	1.3	$\mathcal{I}_{-}$	2.3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4 A	/ A	21	29	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A		18	26	

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Input capacitance	C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	- /	630		pF
Reverse transfer capacitance	C <sub>rss</sub>		-(	46		
Output capacitance	C <sub>oss</sub>		7	(150)	) —	
Gate resistance	r <sub>g</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 5 \text{ MHz}$		14	2.1	Ω
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.		2.6		ns
Switching time (turn-on time)	t <sub>on</sub>		/,-//	7.6		
Switching time (fall time)	t <sub>f</sub>	$(\bigcirc) \qquad (\bigcirc)$	$\widetilde{}$	2.9	_	
Switching time (turn-off time)	t <sub>off</sub>		) –	18	_	

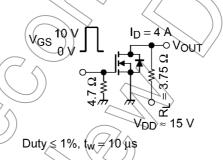


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	$\langle Q_g \rangle$	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$	1	11	_	nC
gate-drain)		$V_{DD} \approx 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 8 \text{ A}$		6.2	_	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		2.3	_	
Gate-drain charge	$\bigcirc$ Q <sub>gd</sub>			2.5	_	
Gate switch charge	$Q_SW$		_	3.5	_	

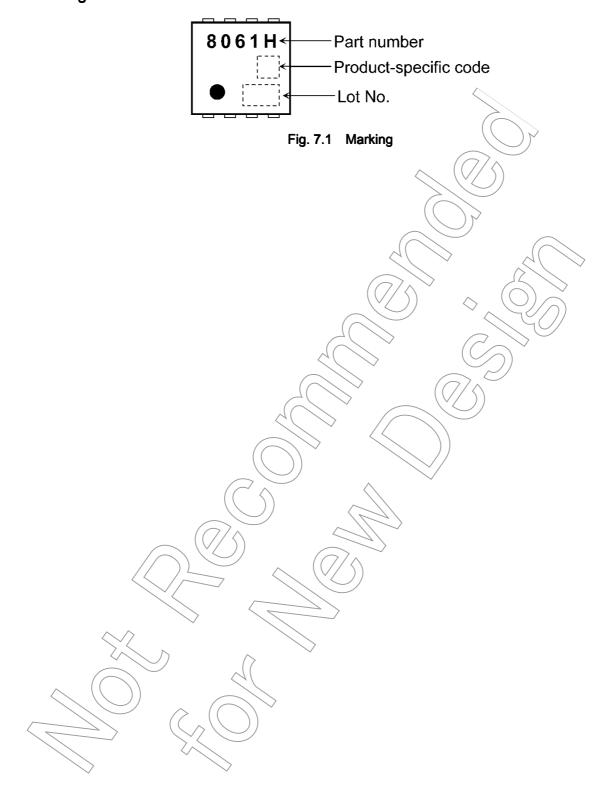
## 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 5)	I <sub>DRP</sub>	_	_	_	24	Α
Diode forward voltage		$V_{DSF}$	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V		_	-1.2	V

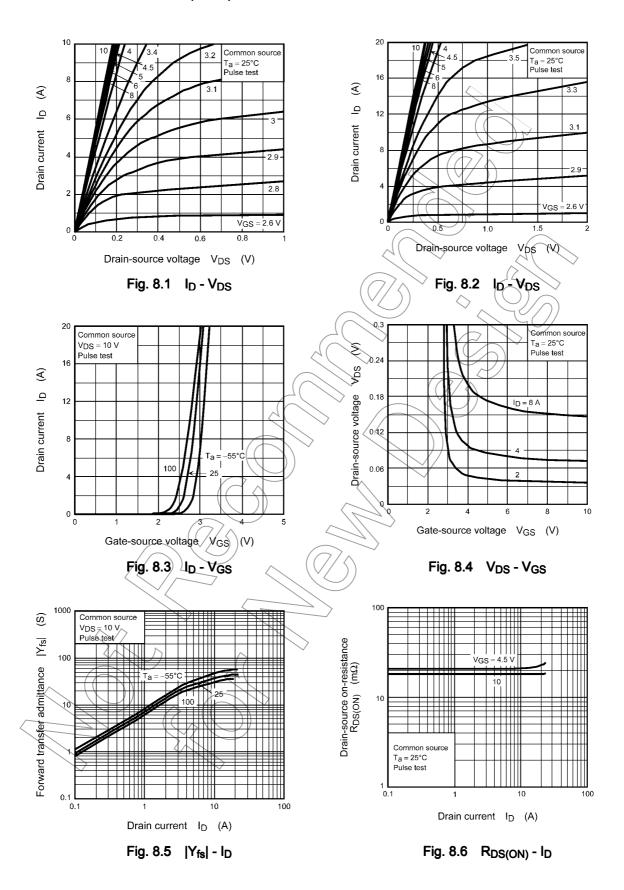
Note 5: Ensure that the channel temperature does not exceed 150°C.



## 7. Marking



### 8. Characteristics Curves (Note)



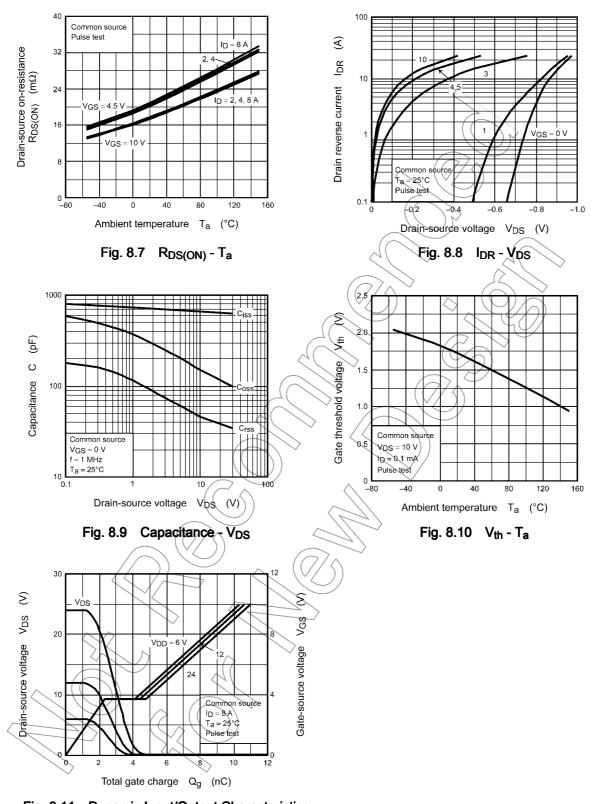


Fig. 8.11 Dynamic Input/Output Characteristics

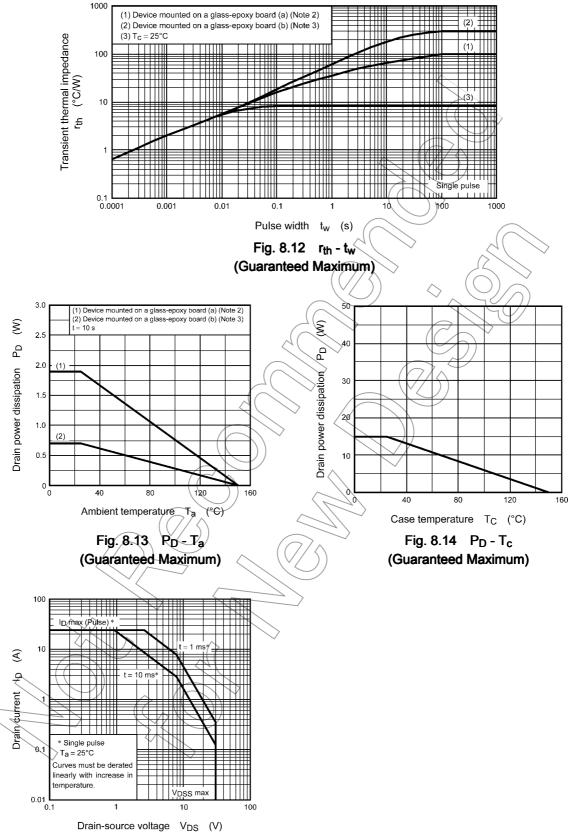


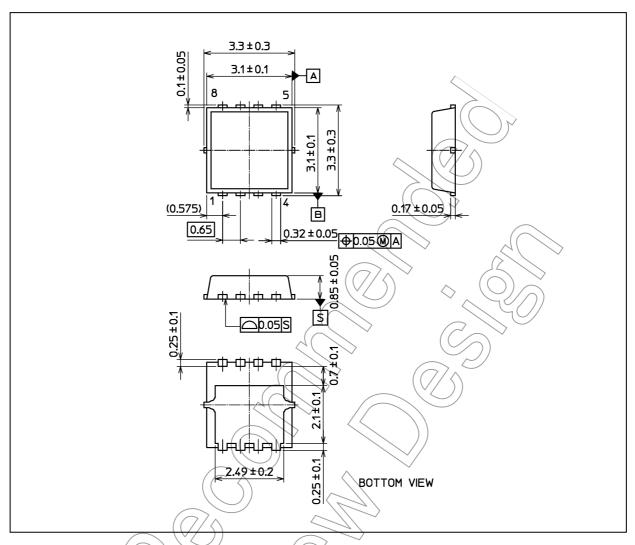
Fig. 8.15 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

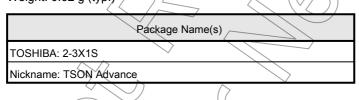


## **Package Dimensions**

Unit: mm



Weight: 0.02 g (typ.)





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